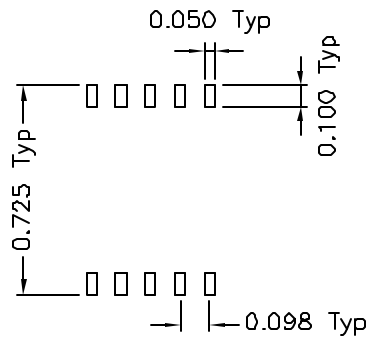
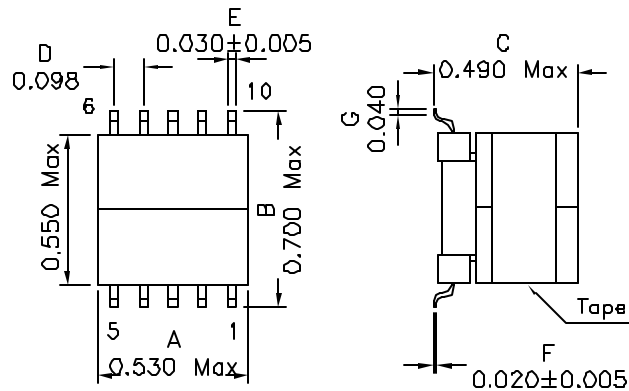
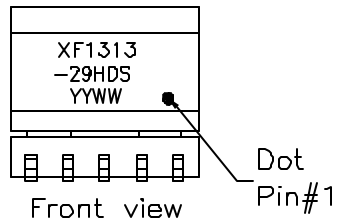
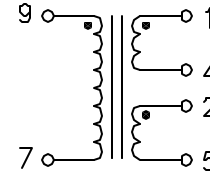


## 1. Dimensions:



Suggested PCB Layout

## 2. Schematic:



## 3. Electrical Specifications: @25°C

OCL: Pins 1-5 3.0mH ±6% @10KHz 0.1V, 0mA, DC  
Tie Pins 2-4

LL: Pins 1-5 22µH Max @100KHz 0.1V,  
Tie Pins 2-4, Short Pins 9-7

CW/W: Pins 9-1 150pF Max @100KHz 0.1V, Tie Pins 2-4

TURNS RATIO: Pins (9-7):(1-5)=1:4.5CT±2%, Tie Pins 2-4

DC Res.: Pins 9-7 0.660 Ohms Max

DC Res.: Pins 2-5 1.65 Ohms Max

DC Res.: Pins 1-4 1.65 Ohms Max

ISOLATION VOLTAGE: 2000Vrms (Chip to Line)

ISOLATION VOLTAGE: 600Vrms (Line to Line)

THD: -82db Max @10KHz 4Vrms

### Notes:

- Solderability: Leads shall meet MIL-STD-202G, Method 208H for solderability.
- Flammability: UL94V-0
- ASTM oxygen index: > 28%
- Insulation System: Class F 155°C. UL file E151556
- Operating Temperature Range: All listed parameters are to be within tolerance from -40°C to +85°C
- Storage Temperature Range: -55°C to +125°C
- Aqueous wash compatible
- SMD Lead Coplanarity: ±0.004" (0.102mm)
- Electrical and mechanical specifications 100% tested
- RoHS Compliant Component
- ULB0950 approved to Supplementary Insulation requirements for a working voltage up to 250V, file #E185868.

<b>XFMRs Inc</b> <a href="http://www.XFMRs.com">www.XFMRs.com</a>	Title: HDSL TRANSFORMER		
	UNLESS OTHERWISE SPECIFIED TOLERANCES: .xxx ±0.010 Dimensions in INCH	P/N: XF1313-29HDS	REV. A
SHEET 1 OF 1	DWN.	Juan Mao	Mar-06-08
	CHK.	YK Liao	Mar-06-08
	APP.	BW	Mar-06-08

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